| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIESS<br>International and Pa | IPC. Bannockl | burn. Illinois. A       | Il rights reserved untions. | inder both              | This docume<br>level parts, t  | ent is a declarati<br>the declaration e | on of the su               | ibstances v<br>s all lower | within the manufactur<br>level materials for w | rer listed i<br>hich the n      | tem. Note:<br>nanufacture | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|---|---------------|-------------------------|-----------------------------|-------------------------|--|---|----------------------------|----------------------------|--|---------------------------------|---------------------------|---|---------------------------------|--|
|   |               |                         |                             | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Material |   |                            |                            |  | ials and M                      | als and Mfg Information   |   |                                 |  |
| upplier Information   |               |                         |                             |                         |  |   |                            |                            |  |                                 |                           |   |                                 |  |
| Company name* Con   |               | Company un              | Company unique ID           |                         |  | Unique ID Authority                     |                            |                            |  | Response Date*                  |                           |   |                                 |  |
| onsemi  |               |                         |                             |                         |  |   |                            |                            |  | 2024-05-21                      |                           |   |                                 |  |
| Contact Name Title - Contact  |               |                         | ct                          |                         |  | Phone - Contact*                        |                            |                            |  | Email - Contact*                |                           |   |                                 |  |
| Product-Env-Stewards Product Env  |               |                         | Enviro Compliance           |                         |  | NA                                      |                            |                            |  | Product-Env-Stewards@onsemi.com |                           |   |                                 |  |
| Authorized Representative* Title - Representative                         |               |                         | resentative                 |                         |  | Phone - Representative*                 |                            |                            | Email - Representative*                        |                                 |                           |   |                                 |  |
| Product-Env-Stewards Produc   |               |                         | roduct Enviro Compliance    |                         |  | NA                                      |                            |                            |  | Product-Env-Stewards@onsemi.com |                           |   |                                 |  |
| Requester Item Number   | Mfr Iten      | n Number                | Mfr Item Name               |                         |  | Effective Date                          | Version Manufacturing Site |                            | Ianufacturing Site                             |                                 | Weight*                   | UOM                                       | Unit Type                       |  |
|   | QSB363        | QSB363GR PHOTOTR T3     |                             | -4 GULLW T&R            |  | 2024-05-21                              |                            | E                          | EVERLGFG                                       |                                 | 18.677                    | mg  | Each                            |  |
| Ianufacturing Proccess Inform   | ation         |                         |                             |                         |  |   |                            |                            |  |                                 |                           |   |                                 |  |
| Terminal Plating / Grid Array M   | Iaterial 7    | ial Terminal Base Alloy |                             | J-STD-020 MSL Rating    |  | Peak Process Body Temperate             |                            | emperature                 | ure Max Time at Peak Temp                      |                                 | ure Num                   | ber of Reflow Cyc                         | les                             |  |
| Matte Tin (Sn) - annealed CU Al   |               | CU Alloy                | 3                           |                         |  | <b>260</b> C                            |                            | С                          | 30 seco  |                                 | ds 3                      |   |                                 |  |
| omments   |               |                         |                             |                         |  |   |                            |                            |  |                                 |                           |   |                                 |  |
| <b>FTENTION: MSL 3 Rated item requir</b>                                  | es Bake and I | Dry Pack (after         | electrical test)            |                         |  |   |                            |                            |  |                                 |                           |   |                                 |  |
| or more information regarding materia                                     | l composition | please refer to         | page 3                      |                         |  |   |                            |                            |  |                                 |                           |   |                                 |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance  | CAS        | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|------------|--------|--------|-----------------|
| Die                  | 0.027  | mg              | Supplier | Silicon (Si)   | 7440-21-3  |        | 0.027  | mg              |
| Die Attach           | 0.051  | mg              | Supplier | Silver (Ag)  | 7440-22-4  |        | 0.0441 | mg              |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin                             | 29690-82-2 |        | 0.0069 | mg              |
| Lead Frame           | 6.38   | mg              | Supplier | Silver (Ag)  | 7440-22-4  |        | 0.032  | mg              |
|                      |        |                 | Supplier | Tin (Sn)   | 7440-31-5  |        | 0.032  | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8  |        | 6.316  | mg              |
| Mold Compound-Black  | 9.009  | mg              | Supplier | Ortho Cresol Novolac Resin                             | 29690-82-2 |        | 4.505  | mg              |
|                      |        |                 | Supplier | 2,4,6-Tris[Bis(Methoxymethyl)Amino]-<br>1,3,5-Triazine | 3089-11-0  |        | 4.504  | mg              |
| Plating              | 3.2    | mg              | Supplier | Tin (Sn)   | 7440-31-5  |        | 3.2    | mg              |
| Wire Bond - Au       | 0.01   | mg              | Supplier | Gold (Au)  | 7440-57-5  |        | 0.01   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).